

## 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

# PCN#20230306005.0 Marking Standardization for Select Devices Information Only

**Date:** March 16, 2023

To: PREMIER FARNELL PCN

#### Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (<u>PCN www admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

#### 20230306005.0 Attachment: 1

## **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months (60 months for Automotive devices). The corresponding customer part number is also listed, if available.

DEVICE	<b>CUSTOMER PART NUMBER</b>
ADS1220IPW	null
AM26LV32EIPWR	null
CD40109BPW	null
CD4094BPWR	null
CD4520BPW	null
INA240A1PWR	null
INA240A2PWR	null
INA240A3PWR	null
INA240A4PWR	null
MAX3232ECPWR	null
SN74LVC157APWRG4	null
TPS2112APWR	null
TRS3221EIPWR	null
CD74HC4053PWR	null

Technical details of this Product Change follow on the next page(s).

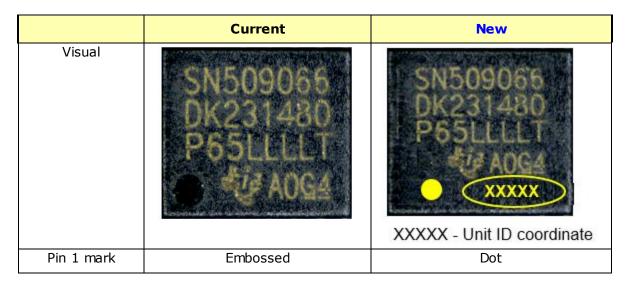
<b>PCN Number:</b> 20230306005.0					PCI	N Date:	March 16, 2023				
Title: Marking Stand				dardization for Select Devices							
Customer Contact: PCN A			N Ma	nager Dept: Quality Servic		es					
Change Type:											
	Asse	mbly Site			Assembly Process				Assembly Materials		
	Design				Datasheet				Mechanical Specification		
☐ Test Site			$\boxtimes$	Device Marking				Test Process			
	Wafe	er Bump Site	e 🔲 Wafer E		Bump Material			Wafer Bump Process			
	Wafe	er Fab Site			Wafer Fab Materials		rials		Wafer Fab Process		
					Part nu	mber cha	ange				

# **PCN Details**

# **Description of Change:**

This notice is to communicate an update in the device symbolization format for the devices in the product affected selection above as follows:

**Change #1**: All devices in this notice will start having the mold cavity id included in the device marking for enhanced device level traceability as follows:



**Change #2:** Devices Symbolization update (for this change below, some of the devices were already on PCN20211123002 for this change):

	Current	New		
**ECAT	Include Value	Remove		
TI Bug	Include	Replace with "TI" text		
Example	#C4851Q #9K G4 #E23 13.10s (109.9 PPH)	18.52s (116.6 PPH)		

<sup>\*\* -</sup> Not all devices have ECAT information included in the symbolization, but for the ones that do, this information will be removed.

## **Reason for Change:**

Marking Standardization

# Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

# Changes to product identification resulting from this PCN:

Device symbolization

## **Product Affected:**

See page 2 above

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com

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